(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property Organization
International Bureau

(43) International Publication Date
5 April 2001 (05.04.2001)

PCT

(10) International Publication Number
WO 01/24232 A1

(51) International Patent Classification[7]: H01L 21/00, G02F 1/15

(21) International Application Number: PCT/US00/26611

(22) International Filing Date:
27 September 2000 (27.09.2000)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
09/408,001 29 September 1999 (29.09.1999) US

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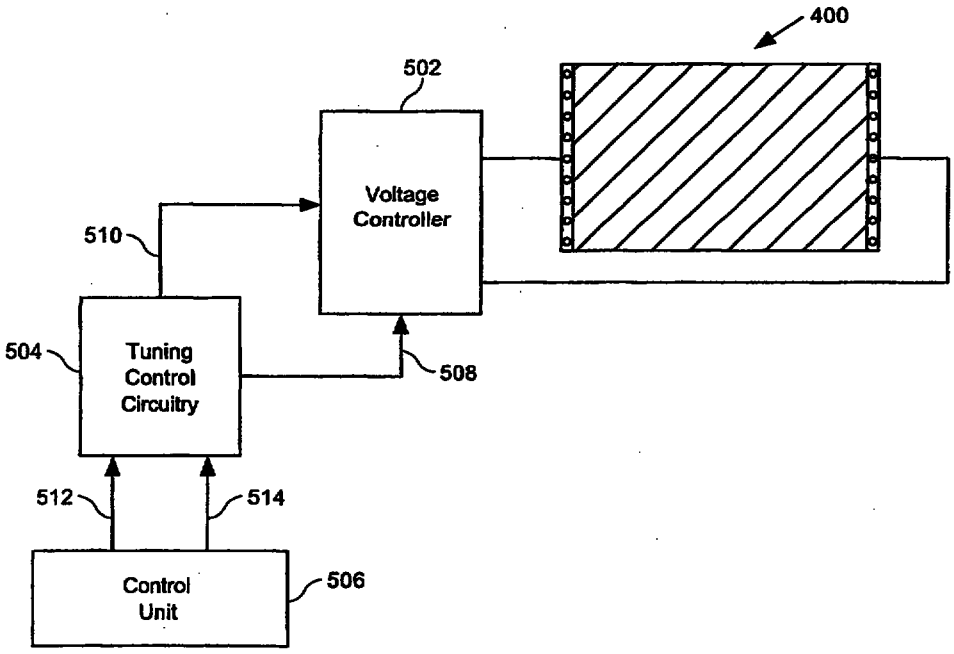
(81) Designated States *(national)*: CN, IL, JP, KR, SG.

(84) Designated States *(regional)*: European patent (AT, BE, CH, CY, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE).

Published:
— *With international search report.*
— *Before the expiration of the time limit for amending the claims and to be republished in the event of receipt of amendments.*

For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.

(54) Title: A METHOD AND SYSTEM FOR REDUCING PHOTO-ASSISTED CORROSION IN WAFERS DURING CLEANING PROCESSES



(57) Abstract: A method and system are provided for reducing and eliminating photo-assisted copper corrosion during a wafer cleaning process. In one example, a method is provided for making a composite material for the cover of a wafer cleaning system. A first transparent layer is formed. A transparency tunable layer is formed over the first transparent layer. Electrical connections are defined between a first portion and a second portion of the transparency tunable layer. And a second transparent layer is formed over the transparency tunable layer.

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